

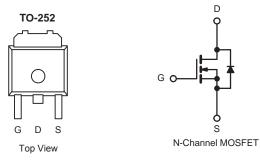
### **DTU09N03S** www.din-tek.jp

## N-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)			
30	0.0 25 at $V_{GS}$ = 10 V	55 <sup>d</sup>	18.2			
50	0.0 63 at V_{GS} = 4.5 V	45 <sup>d</sup>	10.2			

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#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET .
- 100 % Rg and UIS Tested •
- Compliant to RoHS Directive 2002/95/EC ٠

#### **APPLICATIONS**

- Power Supply
- Secondary Synchronous Rectification
- DC/DC Converter •

ABSOLUTE MAXIMUM RATINGS	T <sub>C</sub> = 25 °C, unless oth	erwise noted			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	30	14		
Gate-Source Voltage	V <sub>GS</sub>	± 20	V		
Continuous Drain Current (T <sub>.1</sub> = 150 °C)	T <sub>C</sub> = 25 °C		55 <sup>d</sup>	A	
Continuous Drain Current (1) = 150°C)	T <sub>C</sub> = 70 °C	I_D	45 <sup>d</sup>		
Pulsed Drain Current	I <sub>DM</sub>	165			
Avalanche Current	I <sub>AS</sub>	34			
Single Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AS</sub>	78	mJ	
	T <sub>C</sub> = 25 °C	D	55.5 <sup>b</sup>	w	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C <sup>c</sup>	– P <sub>D</sub> –	2.7		
Operating Junction and Storage Temperature Ra	nge	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	54	°C/W		
Junction-to-Case (Drain)	R <sub>thJC</sub>	2.7	0/11		

Notes:

a. Duty cycle  $\leq$  1 %.

b. See SOA curve for voltage derating.c. When mounted on 1" square PCB (FR-4 material).

d. Package limited.



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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{DS} = 0 V, I_{D} = 250 \mu A$	30			3 V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$	1		3		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS}$ = 0 V, $V_{GS}$ = ± 20 V			± 250	nA	
Zero Gate Voltage Drain Current		$V_{DS}$ = 30 V, $V_{GS}$ = 0 V			1		
	I <sub>DSS</sub>	$V_{DS}$ = 30 V, $V_{GS}$ = 0 V, $T_{J}$ = 125 °C			50	μA	
		$V_{DS}$ = 30 V, $V_{GS}$ = 0 V, $T_{J}$ = 150 °C			250	1	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10$ V, $V_{GS}$ = 10 V	55			А	
Drain Source On State Desistance	Р	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 12 A		0.0125	0.0157	Ω	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 10 A		0.0163	0.0179		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		100		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			578		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 15 V, f = 1 MHz		364			
Reverse Transfer Capacitance	C <sub>rss</sub>			210			
Total Cata Charge <sup>C</sup>	Qg	$V_{DS}$ = 15 V, $V_{GS}$ = 10 V, $I_{D}$ = 20 A		34	56	nC	
Total Gate Charge <sup>c</sup>				20.1	30.2		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{\rm DS}$ = 15 V, $V_{\rm GS}$ = 4.5 V, $I_{\rm D}$ = 20 A		6			
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			5.7			
Gate Resistance	Rg	f = 1 MHz	0.4	2	4	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			8	16		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 15 V, R <sub>I</sub> = 1.5 $\Omega$		9	18		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 10$ Å, $V_{GEN}$ = 10 V, $R_g$ = 1 $\Omega$		35	53	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			9	18		
Drain-Source Body Diode Ratings a	nd Characteris	stics T <sub>C</sub> = 25 °C <sup>b</sup>	•	•	· · · · ·		
Continuous Current	۱ <sub>S</sub>				55	٨	
Pulsed Current	I <sub>SM</sub>			1	165	A	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 10 A, V <sub>GS</sub> = 0 V		0.75	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			34	51	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = 10 A, dI/dt = 100 A/μs		2	3	А	
Reverse Recovery Charge	Q <sub>rr</sub>			34	51	nC	

Notes:

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

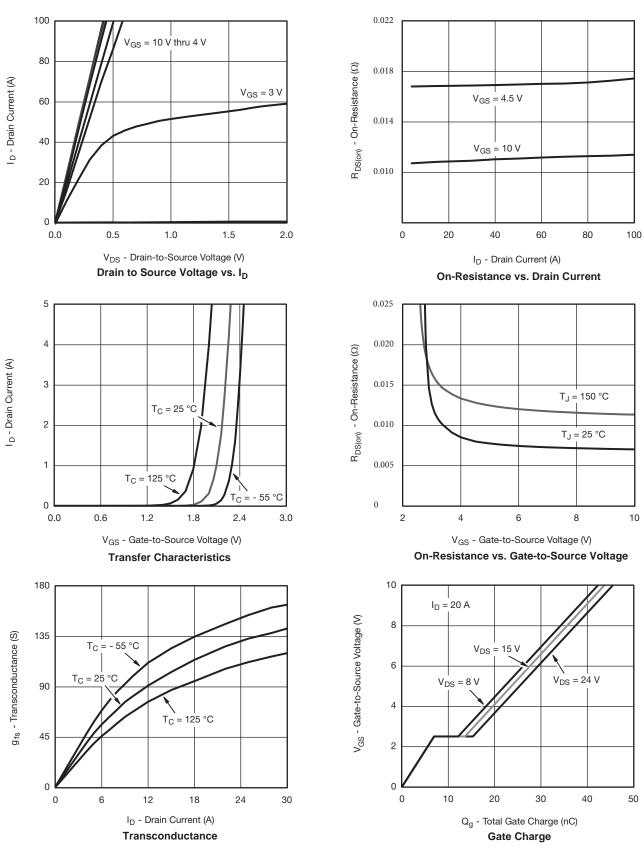
b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

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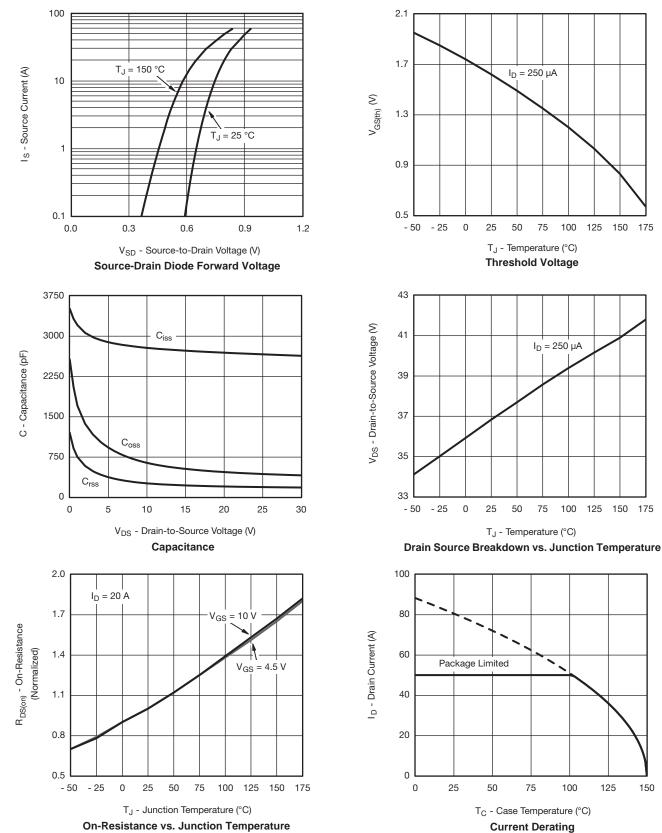


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

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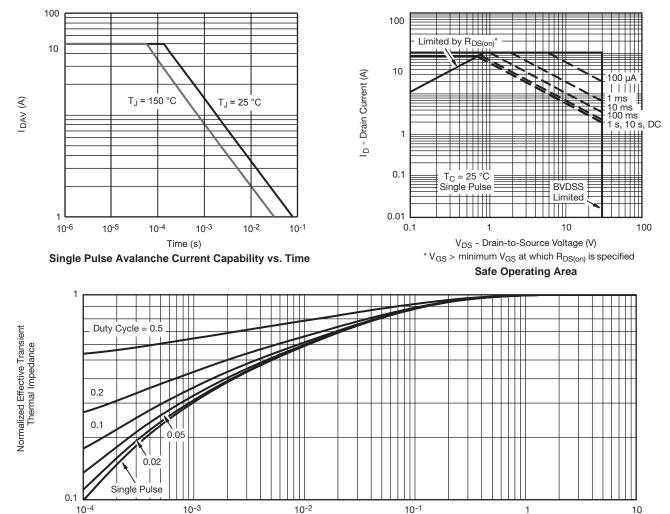
150





#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

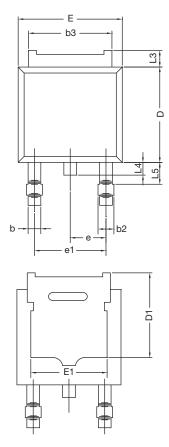
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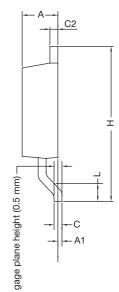


Square Wave Pulse Duration (s) Normalized Thermal Transient Impedance, Junction-to-Case



## **TO-252AA CASE OUTLINE**





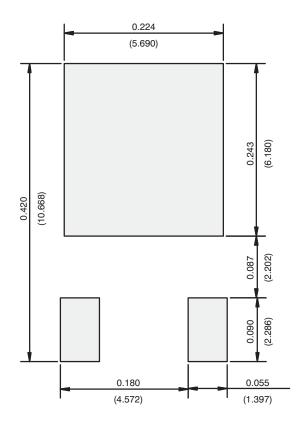
	MILLIMETERS		INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
E	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	BSC	0.090 BSC		
e1	4.56	BSC	0.180 BSC		
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347					

Note

• Dimension L3 is for reference only.



#### **RECOMMENDED MINIMUM PADS FOR DPAK(TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)

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